Computing Continuum for an Intelligent Future

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Aggregate Demand for Computing Accelerating

2000-2010:
Growth rate 68%

74.5 \times 10^{18} transistors shipped in 2010

OR

10 Billion transistors per person on earth

Source: Intel/WSTS
Intel’s Vision
This decade we will create and extend computing technology to connect and enrich the lives of every person on earth.
Building a Continuum of Personal Computing Experiences
Computing Solutions Ingredient Provider

Service
- Intel AppUp®
- Intel Anti-Theft
- McAfee

Software
- MeeGo
- Wind River
- Intel® Software Network
  Connect with developers and Intel engineers

Platform
- IMC*
- Intel® vPro™
- Intel® 核芯显卡
- Intel® Insider

CPU
- Intel® Core™
- Intel® Atom™
- Intel® Xeon™
Leading Processing Technology in Industry

- **2003**: 90 nm
  - Invention of Sige strained silicon technology

- **2005**: 65 nm
  - Second-generation Sige strained silicon technology

- **2007**: 45 nm
  - The invention of high-K metal gate

- **2009**: 32 nm
  - Second-generation high-K metal gate

- **2011**: 22 nm
  - Invention of 3-D tri-gate transistors

**Silicon technology**

- High - L metal gate
- Tri-gate transistor

**Foundation of all computing**

- **37%**
  - Performance increasing in low power states

- **>50%**
  - Power reduction with constant performance

**Source**: Intel

*Compared to Intel 32nm Technology*
IT Industry Contributes to Green Economy

2005
12842*

2020
1595*
5468*
Intel® Data Center Manager (DCM):

Increase energy efficiency in Data Center

- Increasing costs to power and cool
- Running out of Datacenter capacity due to Power & Thermal constraints
- Over-provision racks due to no visibility into server power consumption
- Complexity of managing multi-vendor environments

Power and Cooling spend growing 8x times New Server spend

Intel® DCM Addresses above Challenges through SW and HW Integrated Solutions

Visit http://datacentermanager.intel.com for more information
Intel China- Overview

After 25 years, Intel China has full Org of Sales & Marketing, ATM & Fab, Lab and R&D.

1985, Beijing, first Intel sales and marketing office

1993, Shanghai, Research & Development center, more than 1700 engineers

1998, Beijing, Intel China research center, more than 100 researchers

2003, Chengdu, A7T7, 60,000 square meters, ATM

2007, Dalian, Fab68
From Clusters to Mobile
There’s a Tool to Help

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 krat = Currently Available
Connect WW Developers & Intel Experts online with Software Contents & Interactive Support Platform

Intel Software Network

ISN: 800+ new contents including the latest technology and products introduction each year, 70K+ monthly visits from 300K China developers.

URL: http://software.intel.com/zh-cn
Learn with Intel Experts on the Latest Intel Technology from our Training Courses!

ISC: 30+ training classes covers 1200+ developers each year
Research Direction

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Datacenter & Connected Systems

个人计算机客户平台
PC Client

软件与服务
Software & Services

数字家庭
Digital Home

嵌入式与通信
Embedded & Communication

固态硬盘
Nand & Solution

视觉与并行计算
Visual & Parallel Computing Group

教育市场平台
Education Market Platform

超便携移动终端
Ultra Mobility
“Don’t be encumbered by history. Go off and do something wonderful.”
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